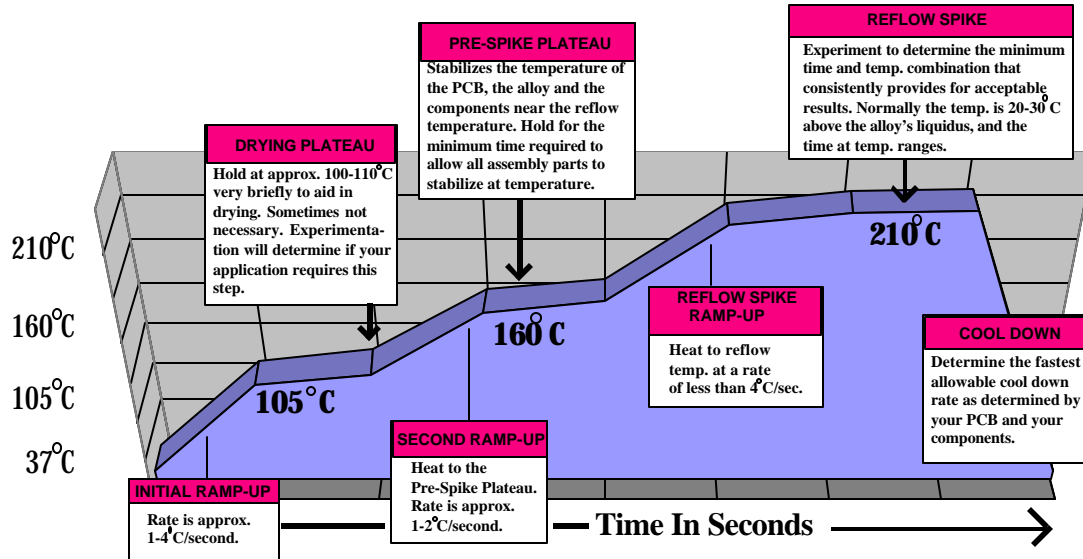


# BGA Surface Mount Adapter Typical Solder Process \*

Recommended solder paste is 63Sn/37Pb.

Recommended solder volume is 0.040 - 0.080 cubic mm with a pad diameter of 0.51 - 0.71mm.

## Generic Reflow Profile [63Sn/37Pb Solder Liquidus @ 183°C (361 F)]



## Test Results for Low Force Contacts (P/N 1427 - 1G) - Test Report No. 92351A

### Durability

50 Cycles at 1 inch per minute, followed by Low Level Resistance Test.

**3.1m Ohm Average, +0.1m Ohm average change**

### Vibration

MIL-STD 1344, Method 2005 Test, Condition III, 15 G's followed by Low Level Resistance Test.

**2.8m Ohm Average, -0.0m Ohm average change**

### Gas Tight

Exposed in a sealed container to concentrated Nitric Acid (HNO<sub>3</sub>) followed by Low Level Resistance Test.

**3.4m Ohm Average, +0.5m Ohm average change**

### Moisture Resistance

Temperature cycling with humidity MIL-STD1344, Method 1002, Type II, followed by Low Level Resistance Test.

**3.4m Ohm Average, +0.7m Ohm average change**

### Temperature Life

MIL-STD 1344, Method 1005, Test Condition 2. 3.8m Ohm Average, +0.8m Ohm average change

### Porosity

MIL-STD 1344, Method 1017

No Porosity

### Contact Resistance

MIL-STD 1344, Method 3002, measured using 100m amp test current. 3.0m Ohm average

### Contact Force

#### Standard Terminal:

Initial Insertion Force:

28.5g average (1.0 oz. average)

#### Initial Withdrawal Force:

18.5 average (0.7 oz. average)

\* Solder process recommendations are presented for guidance only. Factors such as different boards sizes, densities, and equipment will vary actual solder process requirements. Recommendations presented above should be used as starting point only - actual solder process specifications should be developed based on individual requirements and capabilities.



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